

**Features :**

- Isolated mounting base 2500V~
- Pressure contact technology with Increased power cycling capability
- Space and weight saving

Typical Applications

- Various rectifiers
- DC supply for PWM inverter

V_{RSM}	V_{RRM}	Type & Outline
900V	800V	MDx300-08-413F3D
1100V	1000V	MDx300-10-413F3D
1300V	1200V	MDx300-12-413F3D
1500V	1400V	MDx300-14-413F3D
1700V	1600V	MDx300-16-413F3D
1900V	1800V	MDx300-18-413F3D

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	$T_j(^{\circ}\text{C})$	VALUE			UNIT
				Min	Type	Max	
$I_{F(AV)}$	Mean forward current	180° half sine wave 50Hz Single side cooled, $T_c=100^{\circ}\text{C}$	150			300	A
$I_{F(RMS)}$	RMS forward current		150			471	A
I_{RRM}	Repetitive peak current	at V_{RRM}	150			20	mA
I_{FSM}	Surge forward current	10ms half sine wave $V_R=0.6V_{RRM}$	150			9.1	KA
I^2t	I^2t for fusing coordination					414	$\text{A}^2\text{s} \times 10^3$
V_{FO}	Threshold voltage		150			0.75	V
r_F	Forward slope resistance					0.55	m Ω
V_{FM}	Peak forward voltage	$I_{FM}=900\text{A}$	25			1.35	V
$R_{th(j-c)}$	Thermal resistance Junction to case	At 180° sine: Single side cooled per chip				0.13	$^{\circ}\text{C}/\text{W}$
$R_{th(c-h)}$	Thermal resistance case to heatsink	At 180° sine: Single side cooled per chip				0.04	$^{\circ}\text{C}/\text{W}$
V_{iso}	Isolation voltage	50Hz, R.M.S, $t=1\text{min}$, $I_{iso}: 1\text{mA}(\text{max})$		2500			V
F_m	Terminal connection torque(M8)				12.0		N·m
	Mounting torque(M6)				6.0		N·m
T_{stg}	Stored temperature			-40		125	$^{\circ}\text{C}$
W_t	Weight				810		g
Outline	413F3D						

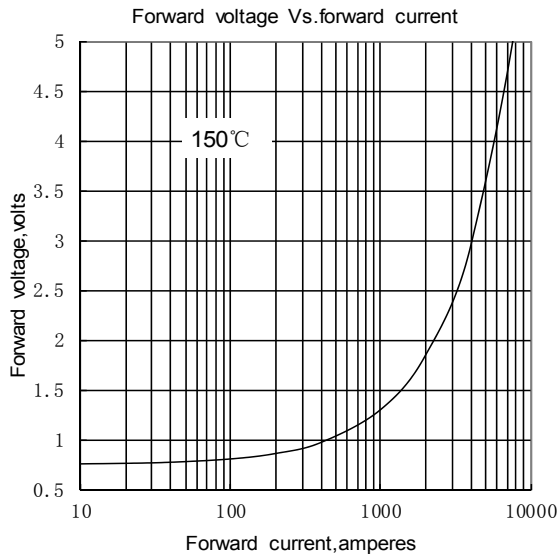


Fig.1

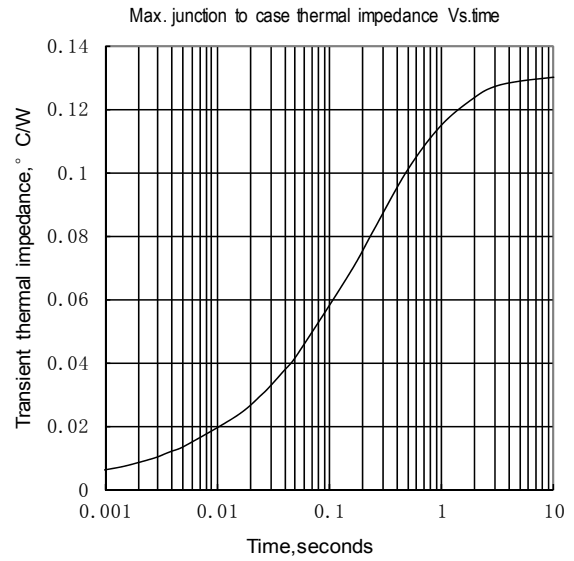


Fig.2

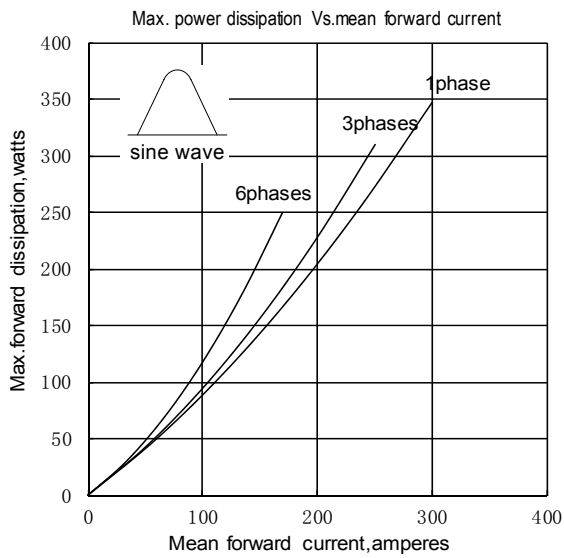


Fig.3

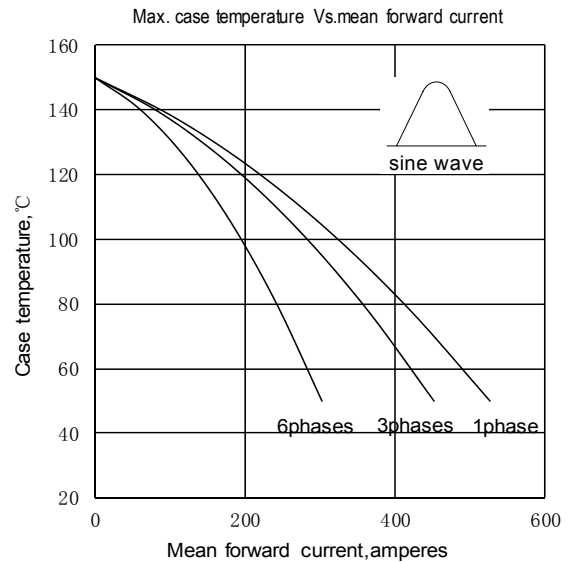


Fig.4

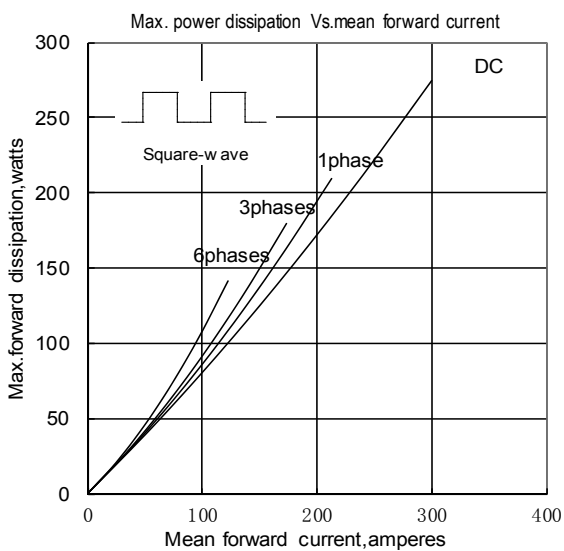


Fig.5

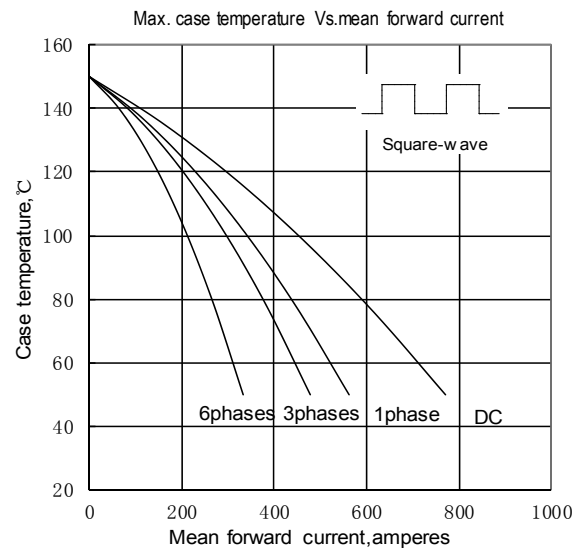


Fig.6

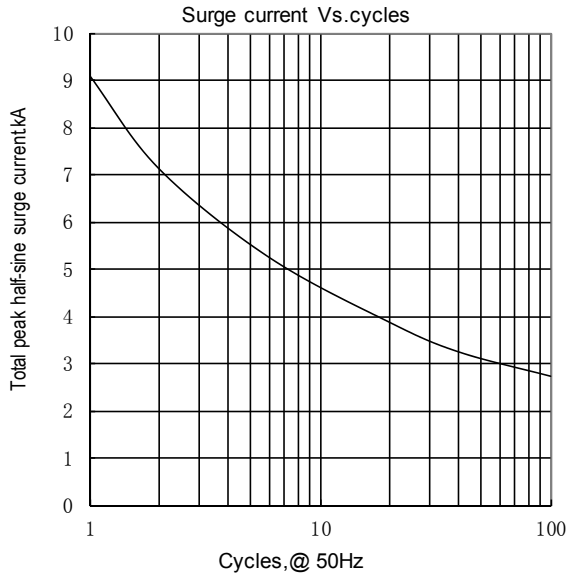


Fig.7

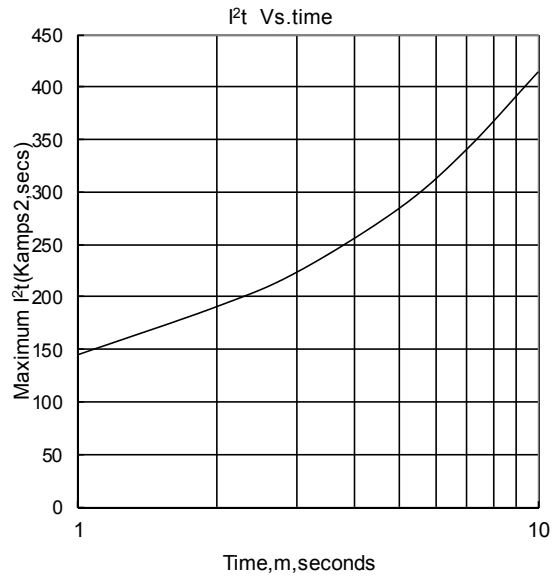
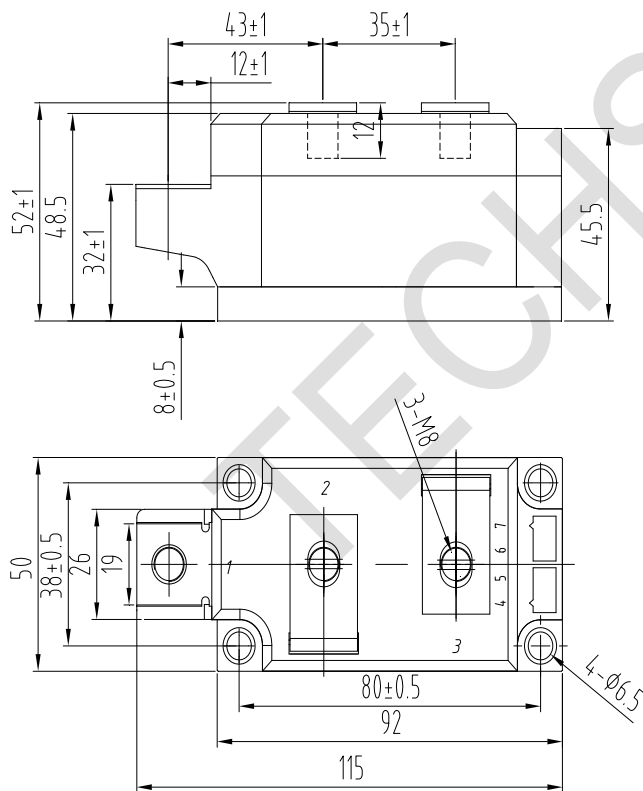
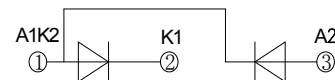


Fig.8

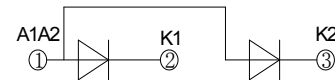
Outline:



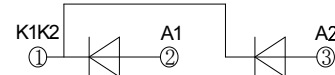
MDC



MDA



MDK



MD

